

Product / Process Change Notification



N° 2020-179-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Introduction of new mold compound for dedicated ATSLP packages from Infineon Technologies (Malaysia) Sdn. Bhd.

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **9th April 2021**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates: **“Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”**

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

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► **Products affected:** Please refer to attached affected product list 1_cip20179_a

► **Detailed Change Information:**

Subject: Introduction of new mold compound for dedicated ATSLP packages from Infineon Technologies (Malaysia) Sdn. Bhd.

Reason: To further ensure our product performance the new mold compound will be introduced.

Description:	<u>Old</u>	<u>New</u>
Mold Compound	■ Mold Compound : KMC 3210 GF	■ Mold Compound : EME G311AC

► **Product Identification:** Internal traceability assured via baunumber, lot number & date code.
No change in SP ordering number.

► **Impact of Change:** No impact on electrical performance. Quality and reliability verified by qualification. There is no change in form, fit and function.

► **Attachments:**

Affected product list	: 1_cip20179_a
Qualification report	: 2_cip20179_a
Customer info package	: 3_cip20179_a

► **Time Schedule:**

- | | |
|-------------------------------|---------------------------|
| ■ Final qualification report: | Available |
| ■ First samples available: | Please refer 3_cip20179_a |
| ■ Intended start of delivery: | Please refer 3_cip20179_a |

If you have any questions, please do not hesitate to contact your local Sales office.

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Introduction of new mold compound for dedicated ATSLP packages from Infineon Technologies
(Malaysia) Sdn. Bhd.



Sales name	SP number	OPN	Package
BGA H1A10 E6327	SP002641708	BGAH1A10E6327XTSA1	ATSLP-10-1
BGA U1A10 E6327	SP001628070	BGAU1A10E6327XTSA1	ATSLP-10-3
BGA V1A10 E6327	SP001628074	BGAV1A10E6327XTSA1	ATSLP-10-1
BGM 12LBA9 E6327	SP001579876	BGM12LBA9E6327XTSA1	ATSLP-9-1
BGM 13HBA9 E6327	SP001510046	BGM13HBA9E6327XTSA1	ATSLP-9-1
BGM 15LA12 E6327	SP001215968	BGM15LA12E6327XTSA1	ATSLP-12-1
BGS 14MA11 E6327	SP001615916	BGS14MA11E6327XTSA1	ATSLP-11-2
BGS 14MPA9 E6327	SP001700518	BGS14MPA9E6327XTSA1	ATSLP-9-3
BGS 16GA14 E6327	SP001313540	BGS16GA14E6327XTSA1	ATSLP-14-7
BGS 16MA12 E6327	SP001646658	BGS16MA12E6327XTSA1	ATSLP-12-10
BGS 18GA14 E6327	SP001313548	BGS18GA14E6327XTSA1	ATSLP-14-9
BGS 18MA12 E6327	SP001646662	BGS18MA12E6327XTSA1	ATSLP-12-10
BGS 18MA14 E6327	SP001641674	BGS18MA14E6327XTSA1	ATSLP-14-10
BGSX 210MA18 E6327	SP001408614	BGSX210MA18E6327XTSA1	ATSLP-18-3
BGSX 212MA18 E6327	SP001408616	BGSX212MA18E6327XTSA1	ATSLP-18-2
BGSX 22G5A10 E6327	SP001777960	BGSX22G5A10E6327XTSA1	ATSLP-10-2
BGSX 44MA12 E6327	SP001716962	BGSX44MA12E6327XTSA1	ATSLP-12-12